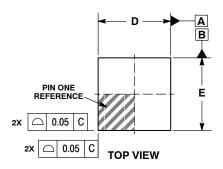
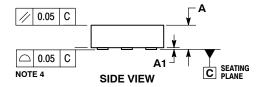
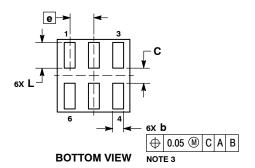


XDFN6 1.2x1.2, 0.4P CASE 711AA-01 **ISSUE O** 

**DATE 12 OCT 2010** 







- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED
  TERMINAL AND IS MEASURED BETWEEN
- 0.15 AND 0.25mm FROM TERMINAL TIPS.
  COPLANARITY APPLIES TO ALL OF THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α		0.40	
A1	0.00 0.05		
b	0.13	0.23	
С	0.20	0.30	
D	1.20 BSC		
E	1.20 BSC		
е	0.40 BSC		
L	0.37	0.48	

## **GENERIC MARKING DIAGRAM\***

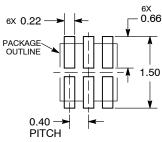


XX = Specific Device Code

MM = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

## **RECOMMENDED MOUNTING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	XDFN6, 1.2 X 1.2, 0.4 P	•	PAGE 1 OF 1

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